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Part Number:

0755860004

Status:

Active

Overview:

ipass

Description:

0.80mm (.031") Pitch, iPass™ I/O SMT Receptacle, Right Angle, External Application, 26 Circuit, 0.38μm (15μ") Gold (Au)

Documents:	
3D Model	Product Specification PS-75586-001 (PDF)
Drawing (PDF)	RoHS Certificate of Compliance (PDF)

Agency Certification

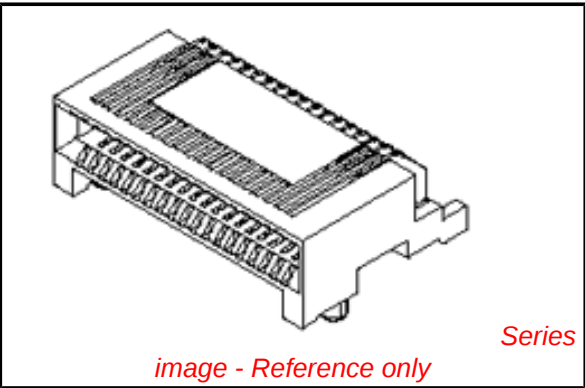
CSA	LR19980
UL	E29179

General

Product Family	I/O Connectors
Series	75586
Application	Wire-to-Board
Component Type	Receptacle
Overview	ipass
Product Name	iPass™, PCI Express*, SAS
Type	N/A

Physical

Boot Color	N/A
Circuits (Loaded)	26
Circuits (maximum)	26
Color - Resin	Black
Durability (mating cycles max)	50
Flammability	94V-0
Gender	Female
Keying to Mating Part	None
Lock to Mating Part	None
Material - Metal	High Performance Alloy (HPA)
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Number of Rows	2
Orientation	Right Angle
PCB Locator	Yes
PCB Retention	None
PCB Thickness Recommended (in)	0.053 In
PCB Thickness Recommended (mm)	1.35 mm
Packaging Type	Embossed Tape on Reel
Panel Mount	No
Pitch - Mating Interface (in)	0.031 In
Pitch - Mating Interface (mm)	0.80 mm
Pitch - Term. Interface (in)	0.031 In
Pitch - Term. Interface (mm)	0.80 mm
Plating min: Mating (μin)	15.2
Plating min: Mating (μm)	0.38
Plating min: Termination (μin)	101.6
Plating min: Termination (μm)	2.54
Polarized to Mating Part	Yes
Polarized to PCB	Yes
Ports	1



EU RoHS

ELV and RoHS Compliant

REACH SVHC

Not Reviewed

Halogen-Free

Status

Not Reviewed

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

75586Series

Mates With

74547 iPass™ Cable Assembly

Use With

74548 I/O Connectors

Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-40°C to +80°C
Termination Interface: Style	Surface Mount
Waterproof / Dustproof	No
Wire Insulation Diameter	N/A
Wire Size AWG	N/A

Electrical

Current - Maximum per Contact	0.5A
Grounding to Panel	N/A
Shielded	No
Voltage - Maximum	30V AC (RMS)/DC

Solder Process Data

Lead-free Process Capability	Reflow Capable (SMT only)
Process Temperature max. C	260

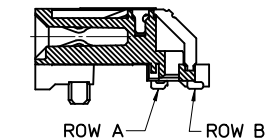
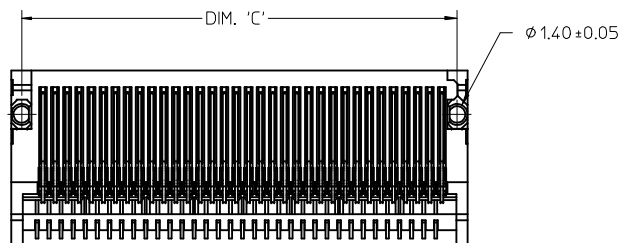
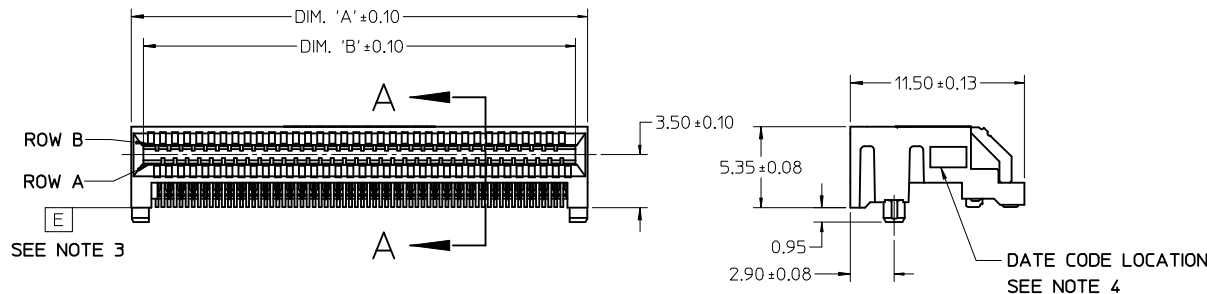
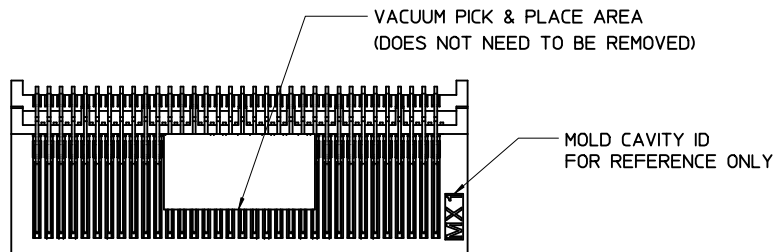
Material Info

Reference - Drawing Numbers

Application Specification	AS-75586-001
Packaging Specification	PK-75586-002, PK-75586-101
Product Specification	PS-75586-001
Sales Drawing	SD-75586-001

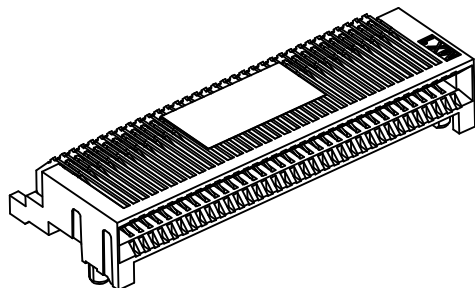
This document was generated on 05/28/2010

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SECTION A-A

68 CIRCUIT ASSEMBLY SHOWN



CIRCUIT SIZE	ITEM NUMBER	PLATING OPTION	DIM 'A'	DIM 'B'	DIM 'C'
26	75586-0004	OPTION 1	13.40	11.80	12.00
26	75586-0009	OPTION 2	13.40	11.80	12.00
36	75586-0003	OPTION 1	17.40	15.80	16.00
36	75586-0008	OPTION 2	17.40	15.80	16.00
38	75586-0010	OPTION 1	18.20	16.60	16.80
38	75586-0011	OPTION 2	18.20	16.60	16.80
50	75586-0001	OPTION 1	23.00	21.40	21.60
50	75586-0006	OPTION 2	23.00	21.40	21.60
68	75586-0002	OPTION 1	30.20	28.60	28.80
68	75586-0007	OPTION 2	30.20	28.60	28.80

NOTES

1. MATERIAL:

HOUSING - HIGH TEMPERATURE THERMOPLASTIC GLASS FILLED,
UL 94V-0, BLACK
TERMINALS - COPPER ALLOY

2. PLATING:

OPTION 1

CONTACT AREA - 0.38 μm MIN GOLD OVER 2.54 μm MIN NICKEL
SOLDER FOOT AREA - 2.54 - 5.09 μm TIN OVER 2.54 μm MIN NICKEL.

OPTION 2

CONTACT AREA - 0.76 μm MIN GOLD OVER 2.54 μm NICKEL
SOLDER AREA - 2.54 - 5.09 μm TIN OVER 2.54 μm MIN NICKEL

3. TERMINAL SOLDER FEET TO BE COPLANAR WITHIN 0.10/0.004 MEASURED FROM FRONT HOUSING STAND OFF (DATUM E)

4. DATE CODE: 4 DIGIT (3 DIGIT DATE, 1 DIGIT YEAR)

5. CIRCUIT IDENTIFIER: SEE APPROPRIATE INDUSTRY SPECIFICATION FOR LOCATION OF PIN 1

6. TO BE USED WITH EXTERNAL CABLES (74546 & 74547 SERIES) AND GUIDE FRAMES (74540 & 74548 SERIES)

7. TESTER/ANALYZER CABLES AVAILABLE (74557 & 74558 SERIES)

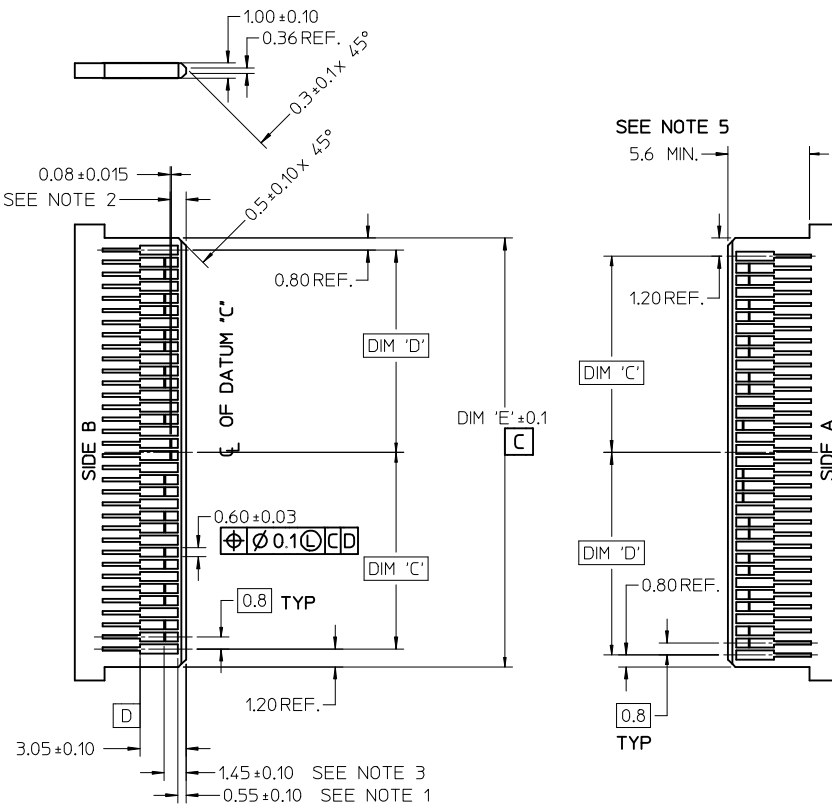
8. PACKAGED PER PACKAGING SPECIFICATION: PK-75586-002

9. CONFORMS TO PRODUCT SPECIFICATION: PS-75586-001

10. THIS PART CONFORMS TO CLASS C REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

iPass™ IS A TRADEMARK OF MOLEX

UPDATE TOLERANCES EC NO: UCP2010-0536 2009/08/27 DRWN:KLANG CHKD: 2009/09/29 APPR:MBANAKIS 2009/09/30	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
					DRAWN BY DATE KREGNIER 07/28/04		TITLE I-PASS R/A CONNECTOR EXTERNAL ASSEMBLY .8 MM PITCH I/O		
					CHECKED BY DATE JLONG 07/29/04		 MOLEX INCORPORATED		
					APPROVED BY DATE RNELSON 07/30/04				
			ANGULAR ±1/2°		MATERIAL NO.		DOCUMENT NO.		SHEET NO.
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-75586-001		1 OF 3			
REV		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



- NOTES:
1. PAD CONFIGURATION FOR FIRST MATE.
 2. PAD CONFIGURATION FOR SECOND MATE.
 3. PAD CONFIGURATION FOR THIRD MATE
(HIGH SPEED SIGNALS).
 4. FOR PIN ASSIGNMENTS AND MATING SEQUENCE
(1ST, 2ND, 3RD), SEE APPLICABLE SPECIFICATION.
 5. MINIMUM STEP REQUIRED IF PCB MADE
WIDER THAN CARD TOUNGE.
 6. SEE 74540 OR 74548 SERIES FOR GUIDE FRAME
FOOT PRINT AND KEEP OUT AREA.

CIRCUIT SIZE	TERM/SIDE 'N'	PEG TO PEG FIRST PAD TO LAST PAD CENTERLINE TO PAD CENTERLINE TO PAD MODULE BOARD WIDTH CONNECTOR WIDTH					
		DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'
26	13	12.00	10.00	4.60	5.00	11.60	13.90
36	18	16.00	14.00	6.60	7.00	15.60	17.90
38	19	16.80	14.80	7.00	7.40	16.40	18.70
50	25	21.60	19.60	9.40	9.80	21.20	23.50
68	34	28.80	26.80	13.00	13.40	28.40	30.70

SEE SHEET 1

EC NO: UCP2010-0536

DRW/KLANG

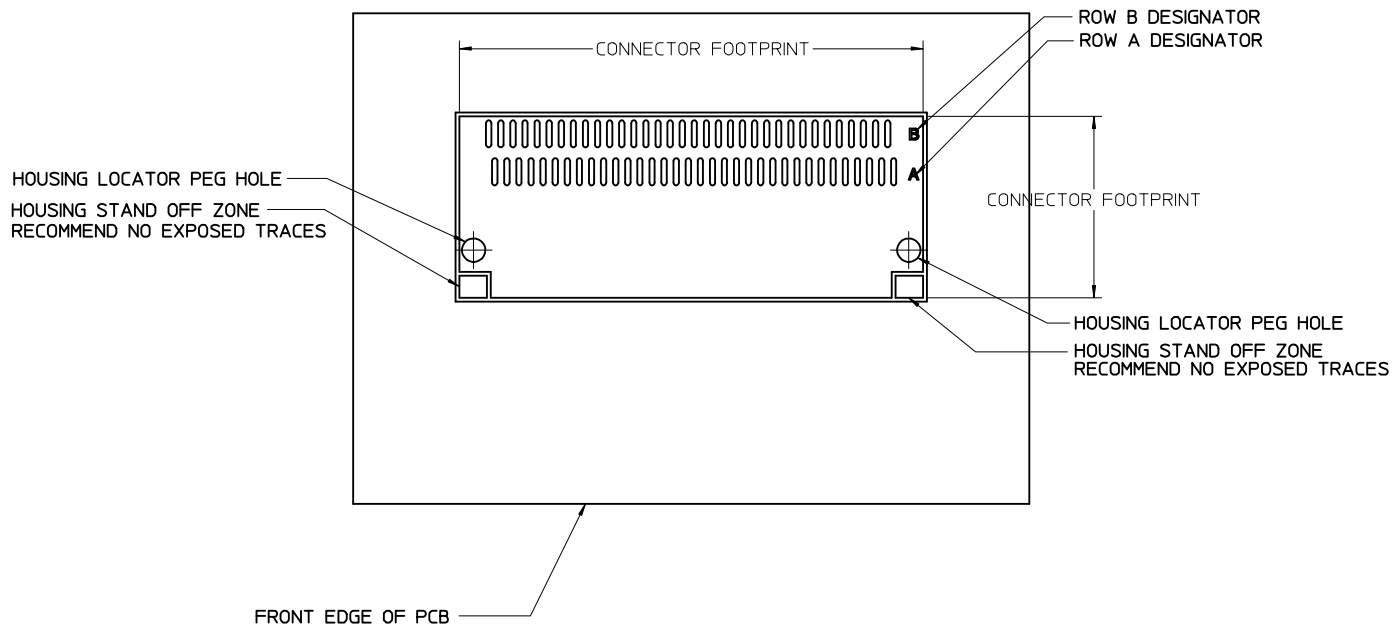
CHKD: 2009/08/27

2009/09/29

2009/09/30

PPR: MRANAK/S

SEE SHEET 1	EC NO: UCP2010-0536 2009/08/27 2009/09/29 CHWKD: LANG APPR: MBANKI S 2009/09/30	DESCRIPTION	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	TITLE I-PASS R/A CONNECTOR EXTERNAL ASSEMBLY .8 MM PITCH I/O MOLEX MOLEX INCORPORATED
				mm	INCH	DRAWN BY KREGNIER	DATE 07/28/04	DOCUMENT NO.		SHEET NO.	
				4 PLACES ± --- ± ---	CHECKED BY JLONG	DATE 07/29/04	SD-75586-001		2 OF 3		
				3 PLACES ± --- ± ---	APPROVED BY RNELSON	DATE 07/30/04					
				2 PLACES ± 0.13 ± ---							
				1 PLACE ± 0.25 ± ---							
				ANGULAR ± 1/2°		SEE SHEET 1					
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



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SEE SHEET 1 EC NO: UCP2010-0536 2009/08/27 DRWN:KLANG CHKD: 2009/09/29 APPR:MBANAKIS 2009/09/30	DESCRIPTION	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	TITLE I-PASS R/A CONNECTOR EXTERNAL ASSEMBLY .8 MM PITCH I/O				
				mm	INCH	DRAWN BY KREGNIER	DATE 07/28/04	MOLEX MOLEX INCORPORATED						
			4 PLACES	± ---	± ---	CHECKED BY JLONG	DATE 07/29/04							
			3 PLACES	± ---	± ---	APPROVED BY RNELSON	DATE 07/30/04				MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
			2 PLACES	± 0.13	± ---	SEE CHART		SD-75586-001			3 OF 3			
			1 PLACE	± 0.25	± ---	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								
			ANGULAR ±1/2°											
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